

### 3.2x1.6mm SMD CHIP LED LAMP

PRELIMINARY SPEC

Part Number: APTL3216SURCK

Hyper Red

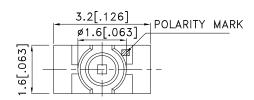
#### **Features**

- 3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE: 2000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL: LEVEL 3.
- RoHS COMPLIANT.

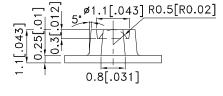
### Description

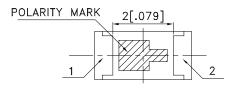
The Hyper Red source color devices are made with In-GaAIP on GaAs substrate Light Emitting Diode.

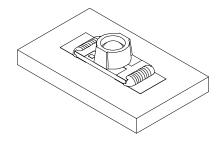
# **Package Dimensions**











- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is  $\pm 0.1 (0.004")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.4. The device has a single mounting surface. The device must be mounted according to the specifications.





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## **Selection Guide**

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		2.	Min.	Тур.	201/2
APTL3216SURCK	Hyper Red (InGaAIP)	WATER CLEAR	280	550	70°

#### Notes:

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2. Luminous intensity/ luminous Flux: +/-15%.

# Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	635		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	1.95	2.5	V	I=20mA
lR	Reverse Current	Hyper Red		10	uA	V <sub>R</sub> =5V

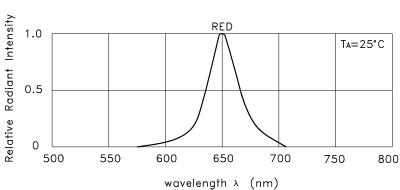
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

### Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	185	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

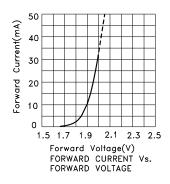
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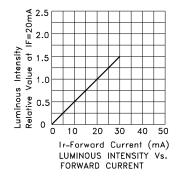


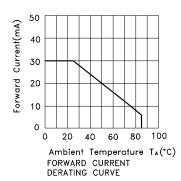
RELATIVE INTENSITY Vs. WAVELENGTH

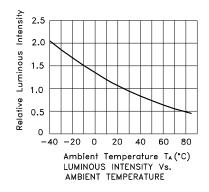
# **Hyper Red**

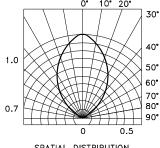
### APTL3216SURCK









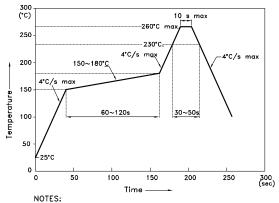


SPATIAL DISTRIBUTION

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## APTL3216SURCK

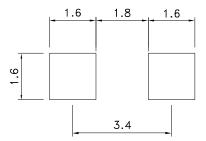
Reflow Soldering Profile For Lead-free SMT Process.



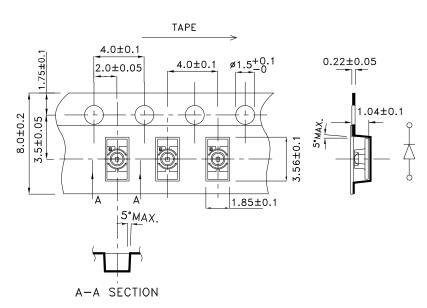
- NOTES:

  1.We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C. 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
   3.Number of reflow process shall be 2 times or less.

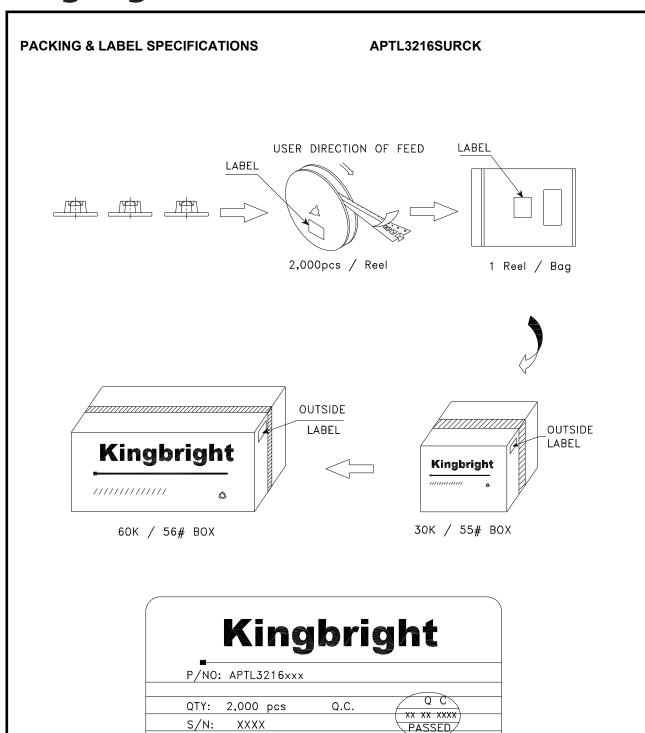
# **Recommended Soldering Pattern** (Units: mm; Tolerance: ± 0.1)



# **Tape Specifications** (Units: mm)



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CODE: XXX

LOT NO:

DATE: JUN/19/2008 DRAWN: Ting.Li

RoHS Compliant

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